

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6124xxxxER-G
Typical Mass: 6 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|---------------|------------|------------|
| Silicon chip | 0.454 | Silicon | 75600 | 7440-21-3 |
| | - | Arsenic | 4 | 7440-38-2 |
| Lead pad | 1.100 | Nickel | 183400 | 7440-02-0 |
| | 0.087 | Silver | 14600 | 7440-22-4 |
| | 0.016 | Gold | 2700 | 7440-57-5 |
| Die attach | 0.020 | Epoxy Resin | 3400 | — |
| | 0.016 | Silica | 2600 | 60676-86-0 |
| Bonding wire | 0.050 | Gold | 8300 | 7440-57-5 |
| | | | | |
| Resin | 3.831 | Silica | 638400 | 60676-86-0 |
| | 0.234 | Epoxy Resin | 39000 | — |
| | 0.192 | Phenol Resin | 31900 | — |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."